

Datasheet revision 1.3

Solder Paste No-Clean Sn42/Bi57.6/Ag0.4 in Jar 250g T5 Mesh

Product Highlights Printing speeds up to 100mm/sec Long stencil life Wide process window Clear residue Low voiding

Excellent wetting compatibility on most board finishes Print grade Compatible with enclosed print heads RoHS II and REACH compliant

Sn42/Bi57.6/Ag0.4	
T5	
15-25	
Synthetic No-Clean	
RELO	
89.5% Metal by Weight	
138°C (281°F)	
Jar 250g	
Refrigerated >6 months, Unrefrigerated >2 months	*See notes below:
	T5 15-25 Synthetic No-Clean REL0 89.5% Metal by Weight 138°C (281°F) Jar 250g

<u>*Shelf Life Notes:</u> Chip Quik® solder paste is good past its quoted shelf life, regardless of refrigeration. Before use, visually inspect the solder paste to ensure it is not dried out or clumpy, or check stencil release. If stored in a jar, stir the product thoroughly for 2-3 minutes before inspection and use.

Chip Quik® solder paste is manufactured using Made in USA high quality synthetic flux and precision atomized metal powder. Chip Quik® solder paste is guaranteed for 12 months from date of manufacture, regardless of refrigeration. If you have any issues with our solder paste, please contact Chip Quik® directly for no charge warranty replacement. Please retain original bill of sale, and solder paste in original container as we may request its return for internal R&D testing purposes.

Printer Operation

Print Speed: 25-100mm/sec Squeegee Pressure: 70-250g/cm of blade Under Stencil Wipe: Once every 10-25 prints, or as necessary

Stencil Life

>8 hours @ 20-50% RH 22-28°C (72-82°F) >4 hours @ 50-70% RH 22-28°C (72-82°F)

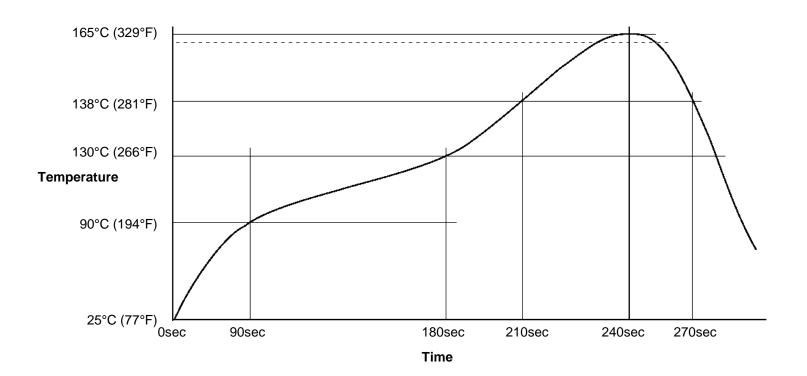
Stencil Cleaning Automated stencil cleaning systems for both stencil and misprinted boards. Manual cleaning using isopropyl alcohol (IPA).

Storage and Handling

Refrigerate at 3-8°C (37-46°F). Do not freeze. Allow 4 hours for solder paste to reach an operating temperature of 20-25°C (68-77°F) before use.

Transportation

This product has no shipping restrictions. Shipping below 0°C (32°F) or above 25°C (77°F) for normal transit times by ground or air will not impact this product's stated shelf life.



Test Results

Result
L: No breakthrough
L: No corrosion
L: <0.5%
L: <1 decade drop (No-clean)
L: ≥100MΩ (No-clean)
48g
Print: 125-180, Dispense: 90-130
Clear and free from precipitation
Compliant
Contains no substance >0.1% w/w that is listed as a SVHC or restricted for use in solder materials

Conforms to the following Industry Standards:	
J-STD-004B, Amendment 1 (Solder Fluxes):	Yes
J-STD-005A (Solder Pastes):	Yes
J-STD-006C, Amendments 1 & 2 (Solder Alloys and Fluxed/Non-Fluxed Solders):	Yes
RoHS 2 Directive 2011/65/EU:	Yes

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 ECO 1 (SNCU1) FLUX B2.1 0,8 MM 250G

 ECO3 (SNCU3) FLUX B2.1 0,8 MM 250 G.
 ECO3 (SNCU3) FLUX B2.1 0,8 MM 1000 G.
 ECO4 (SNAG3CU0.5) FLUX B2.1 0,8 MM 1000G